

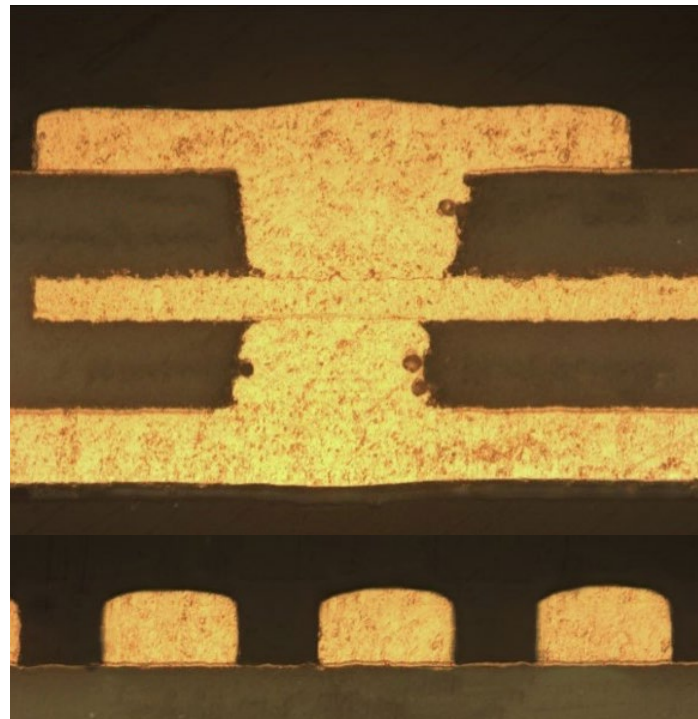
Systek UVF 100

Via Fill and Fine Line Plating for 2-in-1 RDL Applications

Speed. Reliability. Consistency.

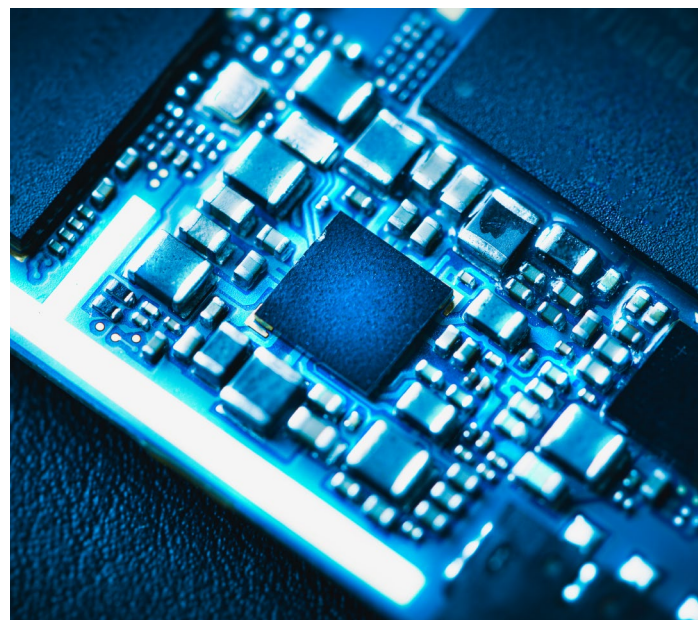
The Systek UVF 100 is an advanced DC acid copper pattern plating process for the plating of blind microvias, laser drilled X-vias, and fine line circuitry in a single solution. The system efficiently fills microvias and X-vias while maintaining excellent trace profiles and co-planarity of lines and pads.

The advanced technology of the Systek UVF 100 makes it the perfect choice for applications such as RDL plating where trace profile and co-planarity across all features is critical. The 2 in 1 capabilities of Systek UVF can be combined with the Systek Semi-additive (SAP) and Embedded Trace (ETS) technologies expanding routing capabilities for the most advanced chip substrate designs today. The deposit meets all standards defined by IPC 6012D, DS, DA, and 6013D.



KEY FEATURES

- Plates fine lines and fills vias in a single solution
- Excellent co-planarity across all features with R values consistently less than 2 microns
- Excellent trace profiles with high values consistently under 15%
- High performance via filling with <math><5\ \mu\text{m}</math> dimple, <math><3\ \mu\text{m}</math> overfill and surface copper thickness between 10 to 15 μm
- Fully analyzable additive system via CVS for high degree of process control



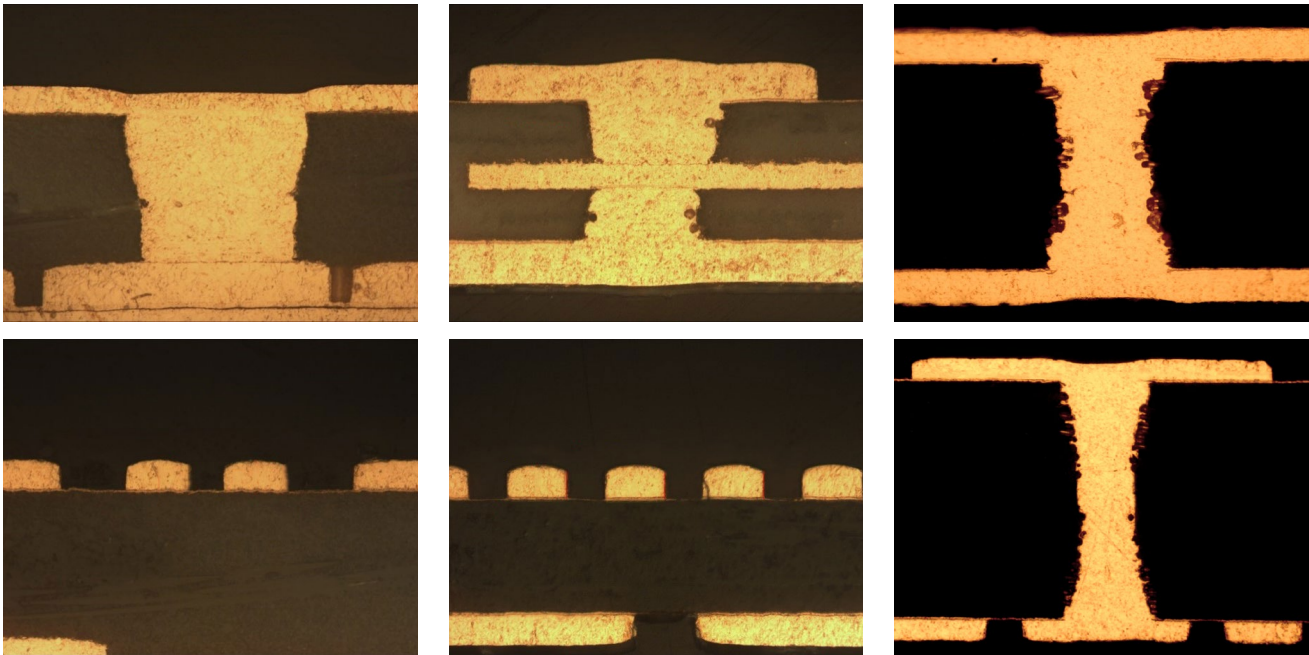
MacDermid Enthone

Systemk UVF 100

Via Fill and Fine Line Plating for 2-in-1 RDL Applications

A Broad Range of Copper Structures and Design Applications.

The Systemk UVF 100 is a versatile copper electroplating process capable of multiple IC substrate applications. From a single plating solution, substrate manufacturers can produce a variety of metallized structures, including filled microvias, filled X-vias, and fine line RDL patterns. The process brings a wide range of panel-level packaging options for substrate manufacturers greatly expanding what is achievable on organic substrates or branch out from wafer-level designs.



Excellent Pad to Trace Height Uniformity / Trace Profile

Trace Width	Pad Width	Avg. R	Profile %	Cross-Sectional Example
25 μm	50 μm	0.5 μm	12%	
15 μm	100 μm	1.5 μm	15%	

The precise plating control provided by the Systemk UVF 100 allows for excellent co-planarity between traces and pads.



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